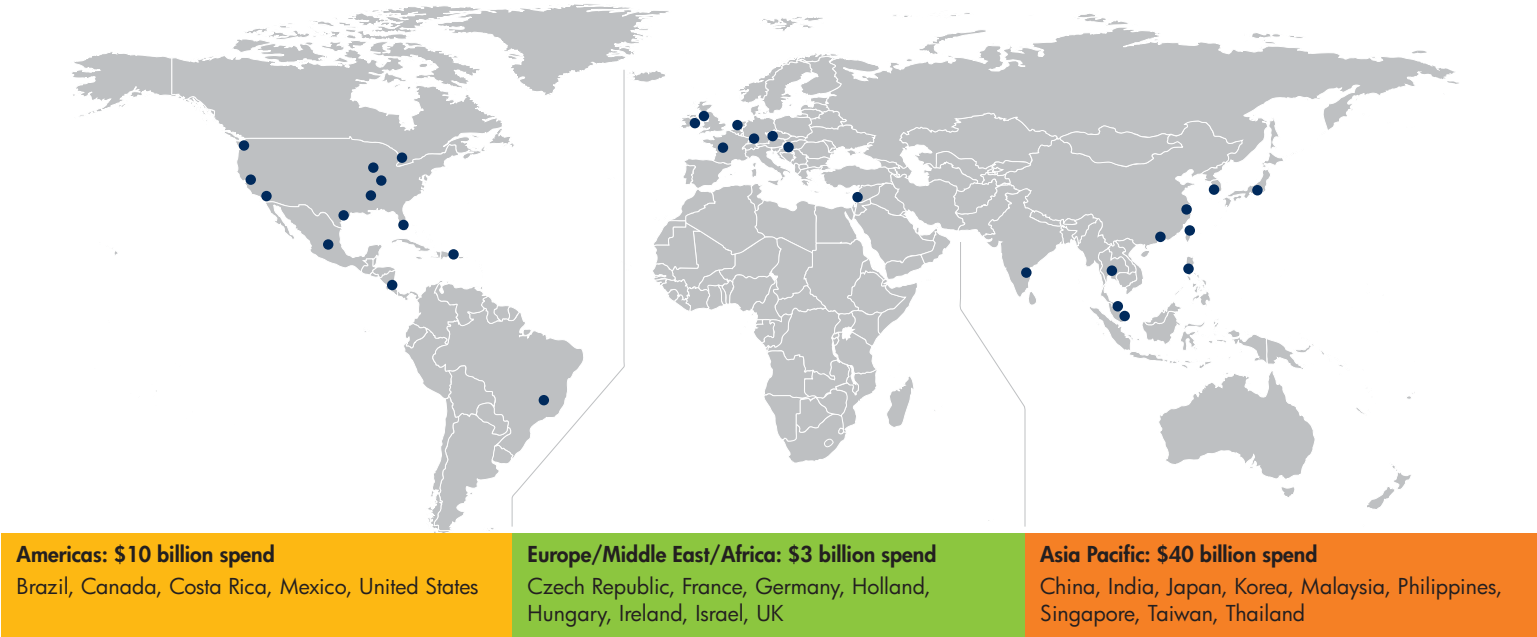


Major locations of HP product materials, components and services suppliers<sup>1</sup>



| Phase of production             | 1 Semiconductor manufacture | 2 Printed circuit board manufacture | 3 Printed circuit board assembly | 4 Final product assembly |
|---------------------------------|-----------------------------|-------------------------------------|----------------------------------|--------------------------|
| Capital investment <sup>2</sup> | High                        | Medium                              | Low                              | Low                      |
| Labor intensity <sup>3</sup>    | Low                         | Low                                 | Medium                           | High                     |
| Skill of labor force            | High                        | High                                | Medium                           | Medium                   |
| Chemical intensity              | High                        | Medium                              | Medium                           | Low                      |
| Environmental impact            | High                        | High                                | Medium                           | Low                      |

Level indication: High Medium Low      Note: This is a simplified view of HP's production that doesn't include all product materials or steps.

<sup>1</sup> Sites on the map are representative and not an exact description. Locations with the largest sourcing expenditures are shown. Actual manufacturing locations may differ in some cases. Does not include HP-owned and operated manufacturing sites (see Operations).

<sup>2</sup> High = Billions of \$; Medium = Hundreds of millions of \$; Low = One-Tens of millions of \$

<sup>3</sup> High = 5,000-25,000 workers; Medium = 1,000-5,000 workers; Low = 50-1,000 workers